

IN THE CLAIMS:

Claims 1-23 (Cancel).

Claim 24 (Original): A semiconductor apparatus comprising:

an organic material substrate;

a die pad formed on the organic material substrate, a semiconductor chip being mounted on the die pad;

ground terminals which are to be grounded;

power supply terminals which are supplied with electrical power;

first conductive patterns which are formed on the organic material substrate and are connected to the ground terminals;

second conductive patterns which are formed on the organic material substrate and are connected to the power supply terminals, in which adjacent two of the first and second conductive patterns are extended inwardly;

chip capacitor mounting pads which are provided at inner ends of the extended first and second conductive patterns; and

chip capacitors which are mounted on the chip capacitor mounting pads so that a decoupling capacitor is provided.

Claim 25 (Original): A semiconductor apparatus according to claim 24, wherein

the chip capacitor mounting pad are adhered to the first and second conductive patterns with a conductive adhesive.

Claim 26 (Original): A semiconductor apparatus according to claim 24, wherein the number of chip capacitors or total amount of capacity of the chip capacitors becomes equivalent for every side of the die pad.

Claim 27 (Original): A semiconductor apparatus according to claim 24, wherein the organic material substrate is provided with cavities in which the chip capacitors are mounted therein.

Claim 28 (Original): A semiconductor apparatus according to claim 27, wherein the chip capacitor mounting pads are arranged at bottoms of the cavities, each of which is provided with side wall plating electrically connected to the corresponding first and second conductive patterns.

Claims 29-48 (Cancel).